

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|--|--|------------------|---------|------------------|
| L1 | 6039 | (interconnect\$5 with (trench via opening hole recess groove damascene dual adj damascene)) with (copper 'cu') | US-PGPU B; USPAT; EPO; JPO | OR | ON | 2005/12/15 07:39 |
| L2 | 6895 | (interconnect\$5 with (trench via opening hole recess groove damascene dual adj damascene)) with (copper 'cu') | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/15 07:39 |
| L3 | 6895 | 2 and (interconnect\$5 trench via opening hole recess groove damascene dual adj damascene copper 'cu') | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/15 07:40 |
| L4 | 677 | 3 and (interconnect\$5 trench via opening hole recess groove damascene dual adj damascene copper 'cu') with nitrogen | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/15 07:41 |
| L5 | 868 | 3 and (interconnect\$5 trench via opening hole recess groove damascene dual adj damascene copper 'cu') with water | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/15 07:41 |

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|-----|------|--|---|----|----|------------------|
| L7 | 31 | 3 and (interconnect\$5 trench via opening hole recess groove damascene dual adj damascene copper 'cu') with (water with nitrogen) | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2005/12/15 07:42 |
| L8 | 3926 | 3 and (interconnect\$5 trench via opening hole recess groove damascene dual adj damascene copper 'cu') with (barrier diffusion) near4 (layer film) | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2005/12/15 07:43 |
| L9 | 2919 | 3 and (copper 'cu') near4 (barrier diffusion) near4 (layer film) | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2005/12/15 07:44 |
| L10 | 785 | 9 and (copper 'cu' barrier diffusion layer film) with nitrogen | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2005/12/15 07:45 |
| L11 | 28 | 9 and (copper 'cu' barrier diffusion layer film) with (nitrogen with water) | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2005/12/15 07:45 |